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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	OTP
EEPROM Size	128 x 8
RAM Size	96 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lce624-04i-ss

1.0 GENERAL DESCRIPTION

The PIC16CE62X are 18 and 20-Pin EPROM-based members of the versatile PIC® family of low-cost, high-performance, CMOS, fully-static, 8-bit microcontrollers with EEPROM data memory.

All PIC® microcontrollers employ an advanced RISC architecture. The PIC16CE62X family has enhanced core features, eight-level deep stack, and multiple internal and external interrupt sources. The separate instruction and data buses of the Harvard architecture allow a 14-bit wide instruction word with separate 8-bit wide data. The two-stage instruction pipeline allows all instructions to execute in a single-cycle, except for program branches (which require two cycles). A total of 35 instructions (reduced instruction set) are available. Additionally, a large register set gives some of the architectural innovations used to achieve a very high performance.

PIC16CE62X microcontrollers typically achieve a 2:1 code compression and a 4:1 speed improvement over other 8-bit microcontrollers in their class.

The PIC16CE623 and PIC16CE624 have 96 bytes of RAM. The PIC16CE625 has 128 bytes of RAM. Each microcontroller contains a 128x8 EEPROM memory array for storing non-volatile information, such as calibration data or security codes. This memory has an endurance of 1,000,000 erase/write cycles and a retention of 40 plus years.

Each device has 13 I/O pins and an 8-bit timer/counter with an 8-bit programmable prescaler. In addition, the PIC16CE62X adds two analog comparators with a programmable on-chip voltage reference module. The comparator module is ideally suited for applications requiring a low-cost analog interface (e.g., battery chargers, threshold detectors, white goods controllers, etc).

PIC16CE62X devices have special features to reduce external components, thus reducing system cost, enhancing system reliability and reducing power consumption. There are four oscillator options, of which the single pin RC oscillator provides a low-cost solution, the LP oscillator minimizes power consumption, XT is a standard crystal, and the HS is for High Speed crystals. The SLEEP (power-down) mode offers power savings. The user can wake-up the chip from SLEEP through several external and internal interrupts and reset.

A highly reliable Watchdog Timer with its own on-chip RC oscillator provides protection against software lock- up.

A UV-erasable CERDIP-packaged version is ideal for code development, while the cost-effective One-Time Programmable (OTP) version is suitable for production in any volume.

Table 1-1 shows the features of the PIC16CE62X mid-range microcontroller families.

A simplified block diagram of the PIC16CE62X is shown in Figure 3-1.

The PIC16CE62X series fits perfectly in applications ranging from multi-pocket battery chargers to low-power remote sensors. The EPROM technology makes customization of application programs (detection levels, pulse generation, timers, etc.) extremely fast and convenient. The small footprint packages make this microcontroller series perfect for all applications with space limitations. Low-cost, low-power, high-performance, ease of use and I/O flexibility make the PIC16CE62X very versatile.

1.1 Development Support

The PIC16CE62X family is supported by a full-featured macro assembler, a software simulator, an in-circuit emulator, a low-cost development programmer and a full-featured programmer. A “C” compiler is also available.

TABLE 1-1: PIC16CE62X FAMILY OF DEVICES

		PIC16CE623	PIC16CE624	PIC16CE625
Clock	Maximum Frequency of Operation (MHz)	20	20	20
Memory	EPROM Program Memory (x14 words)	512	1K	2K
	Data Memory (bytes)	96	96	128
Peripherals	EEPROM Data Memory (bytes)	128	128	128
	Timer Module(s)	TMR0	TMR0	TMR0
	Comparators(s)	2	2	2
	Internal Reference Voltage	Yes	Yes	Yes
Features	Interrupt Sources	4	4	4
	I/O Pins	13	13	13
	Voltage Range (Volts)	2.5-5.5	2.5-5.5	2.5-5.5
	Brown-out Reset	Yes	Yes	Yes
	Packages	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP

All PIC® Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability.
All PIC16CE62X Family devices use serial programming with clock pin RB6 and data pin RB7.

4.2.2.4 PIE1 REGISTER

This register contains the individual enable bit for the comparator interrupt.

REGISTER 4-4: PIE1 REGISTER (ADDRESS 8CH)

U-0	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0
—	CMIE	—	—	—	—	—	—
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
-n = Value at POR reset
-x = Unknown at POR reset

bit 7: **Unimplemented:** Read as '0'

bit 6: **CMIE**: Comparator Interrupt Enable bit
1 = Enables the Comparator interrupt
0 = Disables the Comparator interrupt

bit 5-0: **Unimplemented**: Read as '0'

4.2.2.5 PIR1 REGISTER

This register contains the individual flag bit for the comparator interrupt.

Note:	Interrupt flag bits get set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

REGISTER 4-5: PIR1 REGISTER (ADDRESS 0CH)

U-0	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0
—	CMIF	—	—	—	—	—	—
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
-n = Value at POR reset
-x = Unknown at POR reset

bit 7: **Unimplemented:** Read as '0'

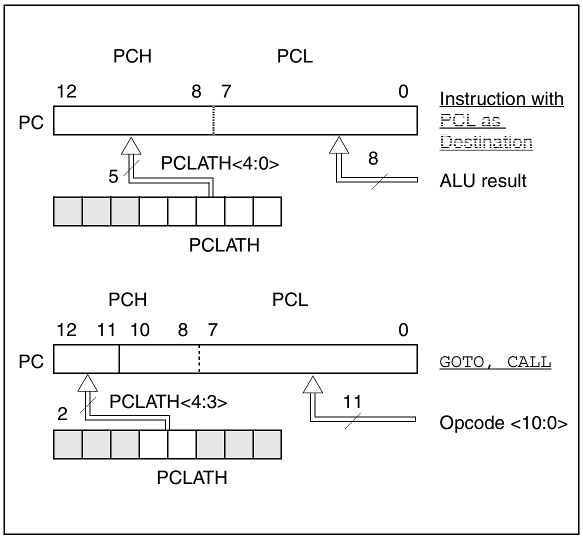
bit 6: **CMIF**: Comparator Interrupt Flag bit
1 = Comparator input has changed
0 = Comparator input has not changed

bit 5-0: **Unimplemented**: Read as '0'

4.3 PCL and PCLATH

The program counter (PC) is 13 bits wide. The low byte comes from the PCL register, which is a readable and writable register. The high byte (PC<12:8>) is not directly readable or writable and comes from PCLATH. On any reset, the PC is cleared. Figure 4-6 shows the two situations for the loading of the PC. The upper example in the figure shows how the PC is loaded on a write to PCL (PCLATH<4:0> $\rightarrow$ PCH). The lower example in the figure shows how the PC is loaded during a `CALL` or `GOTO` instruction (PCLATH<4:3> $\rightarrow$ PCH).

FIGURE 4-6: LOADING OF PC IN DIFFERENT SITUATIONS



4.3.1 COMPUTED GOTO

A computed GOTO is accomplished by adding an offset to the program counter (`ADDWF PCL`). When doing a table read using a computed GOTO method, care should be exercised if the table location crosses a PCL memory boundary (each 256 byte block). Refer to the application note, *"Implementing a Table Read"* (AN556).

4.3.2 STACK

The PIC16CE62X family has an 8 level deep x 13-bit wide hardware stack (Figure 4-2 and Figure 4-3). The stack space is not part of either program or data space and the stack pointer is not readable or writable. The PC is PUSHed onto the stack when a `CALL` instruction is executed or an interrupt causes a branch. The stack is POPed in the event of a `RETURN`, `RETLW` or a `RETFIE` instruction execution. PCLATH is not affected by a PUSH or POP operation.

The stack operates as a circular buffer. This means that after the stack has been PUSHed eight times, the ninth push overwrites the value that was stored from the first push. The tenth push overwrites the second push (and so on).

Note 1:	There are no STATUS bits to indicate stack overflow or stack underflow conditions.
Note 2:	There are no instruction/mnemonics called `PUSH` or `POP`. These are actions that occur from the execution of the `CALL`, `RETURN`, `RETLW` and `RETFIE` instructions or the vectoring to an interrupt address.

NOTES:

5.0 I/O PORTS

The PIC16CE62X parts have two ports, PORTA and PORTB. Some pins for these I/O ports are multiplexed with an alternate function for the peripheral features on the device. In general, when a peripheral is enabled, that pin may not be used as a general purpose I/O pin.

5.1 PORTA and TRISA Registers

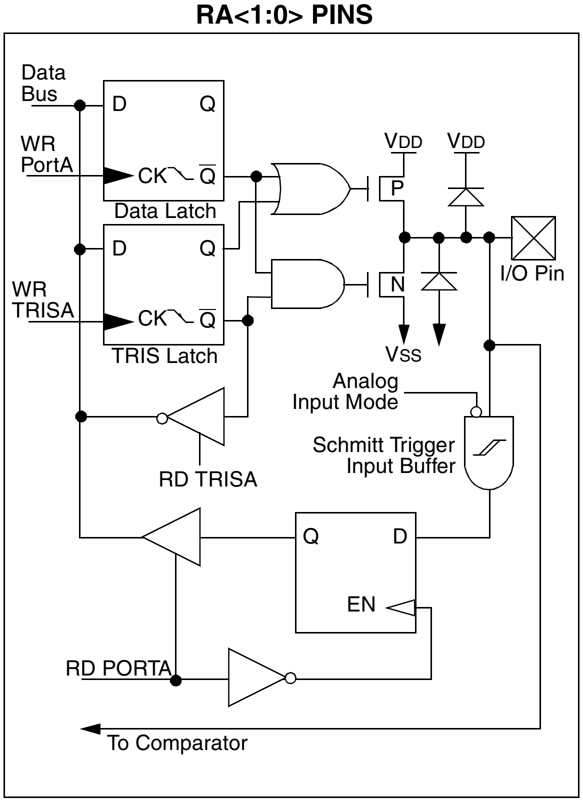
PORTA is a 5-bit wide latch. RA4 is a Schmitt Trigger input and an open drain output. Port RA4 is multiplexed with the T0CKI clock input. All other RA port pins have Schmitt Trigger input levels and full CMOS output drivers. All pins have data direction bits (TRIS registers), which can configure these pins as input or output.

A '1' in the TRISA register puts the corresponding output driver in a hi- impedance mode. A '0' in the TRISA register puts the contents of the output latch on the selected pin(s).

Reading the PORTA register reads the status of the pins, whereas writing to it will write to the port latch. All write operations are read-modify-write operations. So a write to a port implies that the port pins are first read, then this value is modified and written to the port data latch.

The PORTA pins are multiplexed with comparator and voltage reference functions. The operation of these pins are selected by control bits in the CMCON (Comparator Control Register) register and the VRCON (Voltage Reference Control Register) register. When selected as a comparator input, these pins will read as '0's.

FIGURE 5-1: BLOCK DIAGRAM OF RA<1:0> PINS



Note:	On reset, the TRISA register is set to all inputs. The digital inputs are disabled and the comparator inputs are forced to ground to reduce excess current consumption.

TRISA controls the direction of the RA pins, even when they are being used as comparator inputs. The user must make sure to keep the pins configured as inputs when using them as comparator inputs.

The RA2 pin will also function as the output for the voltage reference. When in this mode, the VREF pin is a very high impedance output. The user must configure TRISA<2> bit as an input and use high impedance loads.

In one of the comparator modes defined by the CMCON register, pins RA3 and RA4 become outputs of the comparators. The TRISA<4:3> bits must be cleared to enable outputs to use this function.

EXAMPLE 5-1: INITIALIZING PORTA

```
CLRF   PORTA        ;Initialize PORTA by setting
                    ;output data latches
MOVLW  0X07         ;Turn comparators off and
MOVWF  CMCON        ;enable pins for I/O
                    ;functions
BSF    STATUS, RP0  ;Select Bank1
MOVLW  0x1F         ;Value used to initialize
                    ;data direction
MOVWF  TRISA        ;Set RA<4:0> as inputs
                    ;TRISA<7:5> are always
                    ;read as '0'.
```

FIGURE 5-2: BLOCK DIAGRAM OF RA2 PIN

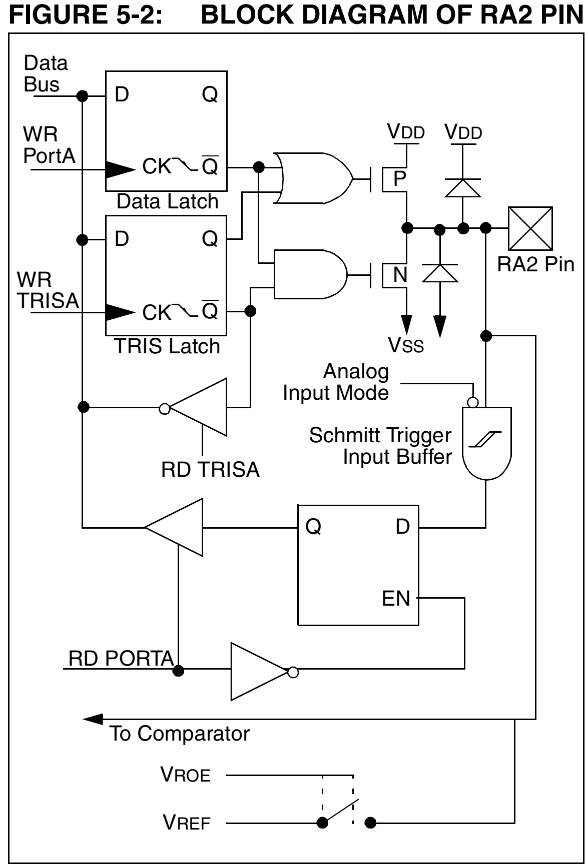
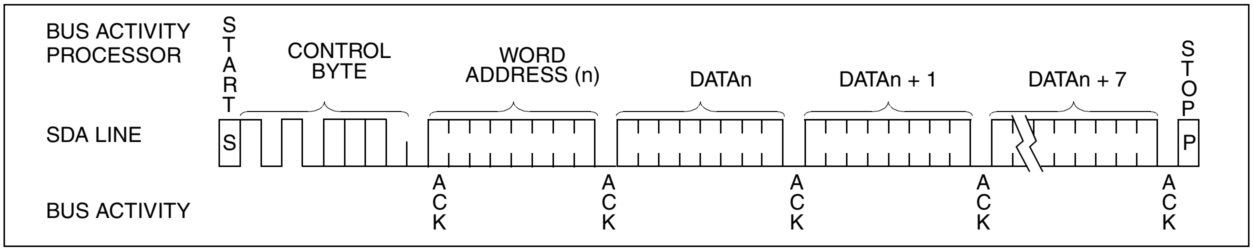


FIGURE 6-6: PAGE WRITE



6.5 Read Operation

Read operations are initiated in the same way as write operations with the exception that the R/$\overline{W}$ bit of the EEPROM address is set to one. There are three basic types of read operations: current address read, random read, and sequential read.

6.6 Current Address Read

The EEPROM contains an address counter that maintains the address of the last word accessed, internally incremented by one. Therefore, if the previous access (either a read or write operation) was to address n, the next current address read operation would access data from address n + 1. Upon receipt of the EEPROM address with R/$\overline{W}$ bit set to one, the EEPROM issues an acknowledge and transmits the eight bit data word. The processor will not acknowledge the transfer, but does generate a stop condition and the EEPROM discontinues transmission (Figure 6-7).

6.7 Random Read

Random read operations allow the processor to access any memory location in a random manner. To perform this type of read operation, first the word address must be set. This is done by sending the word address to the EEPROM as part of a write operation. After the word address is sent, the processor generates a start condition following the acknowledge. This terminates the write operation, but not before the internal address pointer is set. Then the processor issues the control byte again, but with the R/$\overline{W}$ bit set to a one. The EEPROM will then issue an acknowledge and transmits the eight bit data word. The processor will not acknowledge the transfer, but does generate a stop condition and the EEPROM discontinues transmission (Figure 6-8).

6.8 Sequential Read

Sequential reads are initiated in the same way as a random read except that after the EEPROM transmits the first data byte, the processor issues an acknowledge as opposed to a stop condition in a random read. This directs the EEPROM to transmit the next sequentially addressed 8-bit word (Figure 6-9).

To provide sequential reads, the EEPROM contains an internal address pointer which is incremented by one at the completion of each operation. This address pointer allows the entire memory contents to be serially read during one operation.

6.9 Noise Protection

The EEPROM employs a VCC threshold detector circuit, which disables the internal erase/write logic if the VCC is below 1.5 volts at nominal conditions.

The SCL and SDA inputs have Schmitt trigger and filter circuits, which suppress noise spikes to assure proper device operation even on a noisy bus.

7.0 TIMER0 MODULE

The Timer0 module timer/counter has the following features:

- 8-bit timer/counter
- Readable and writable
- 8-bit software programmable prescaler
- Internal or external clock select
- Interrupt on overflow from FFh to 00h
- Edge select for external clock

Figure 7-1 is a simplified block diagram of the Timer0 module.

Timer mode is selected by clearing the T0CS bit (OPTION<5>). In timer mode, the TMR0 will increment every instruction cycle (without prescaler). If Timer0 is written, the increment is inhibited for the following two cycles (Figure 7-2 and Figure 7-3). The user can work around this by writing an adjusted value to TMR0.

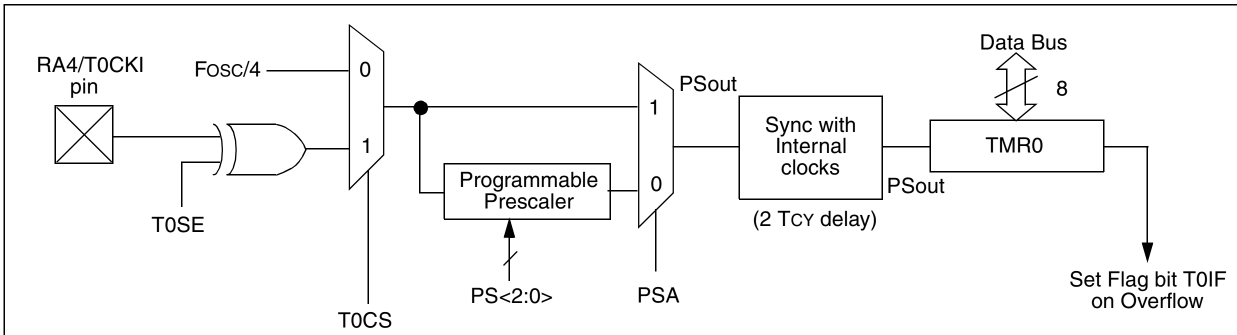
Counter mode is selected by setting the T0CS bit. In this mode Timer0 will increment either on every rising or falling edge of pin RA4/T0CKI. The incrementing edge is determined by the source edge (T0SE) control bit (OPTION<4>). Clearing the T0SE bit selects the rising edge. Restrictions on the external clock input are discussed in detail in Section 7.2.

The prescaler is shared between the Timer0 module and the Watchdog Timer. The prescaler assignment is controlled in software by the control bit PSA (OPTION<3>). Clearing the PSA bit will assign the prescaler to Timer0. The prescaler is not readable or writable. When the prescaler is assigned to the Timer0 module, prescale value of 1:2, 1:4, ..., 1:256 are selectable. Section 7.3 details the operation of the prescaler.

7.1 Timer0 Interrupt

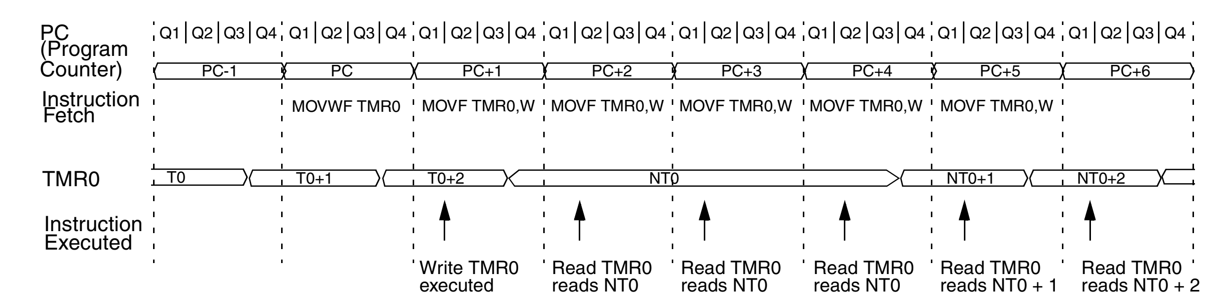
Timer0 interrupt is generated when the TMR0 register timer/counter overflows from FFh to 00h. This overflow sets the T0IF bit. The interrupt can be masked by clearing the T0IE bit (INTCON<5>). The T0IF bit (INTCON<2>) must be cleared in software by the Timer0 module interrupt service routine before re-enabling this interrupt. The Timer0 interrupt cannot wake the processor from SLEEP since the timer is shut off during SLEEP. See Figure 7-4 for Timer0 interrupt timing.

FIGURE 7-1: TIMER0 BLOCK DIAGRAM



Note 1: Bits T0SE, T0CS, PS2, PS1, PS0 and PSA are located in the OPTION register.
2: The prescaler is shared with Watchdog Timer (Figure 7-6)

FIGURE 7-2: TIMER0 (TMR0) TIMING: INTERNAL CLOCK/NO PRESCALER



7.3.1 SWITCHING PRESCALER ASSIGNMENT

The prescaler assignment is fully under software control (i.e., it can be changed “on-the-fly” during program execution). To avoid an unintended device RESET, the following instruction sequence (Example 7-1) must be executed when changing the prescaler assignment from Timer0 to WDT.

EXAMPLE 7-1: CHANGING PRESCALER (TIMER0→WDT)

```
 1.BCF    STATUS, RP0  ;Skip if already in
                       ; Bank 0
 2.CLRWDT              ;Clear WDT
 3.CLRF   TMR0         ;Clear TMR0 & Prescaler
 4.BSF    STATUS, RP0  ;Bank 1
 5.MOVLW  '00101111'b  ;These 3 lines (5, 6, 7)
 6.MOVWF  OPTION       ; are required only if
                       ; desired PS<2:0> are
 7.CLRWDT              ; 000 or 001
 8.MOVLW  '00101xxx'b  ;Set Postscaler to
 9.MOVWF  OPTION       ; desired WDT rate
10.BCF    STATUS, RP0  ;Return to Bank 0
```

To change prescaler from the WDT to the TMR0 module, use the sequence shown in Example 7-2. This precaution must be taken even if the WDT is disabled.

EXAMPLE 7-2: CHANGING PRESCALER (WDT→TIMER0)

```
CLRWDT                 ;Clear WDT and
                       ;prescaler
BSF     STATUS, RP0
MOVLW   b'xxxx0xxx'    ;Select TMR0, new
                       ;prescale value and
                       ;clock source
MOVWF   OPTION_REG
BCF     STATUS, RP0
```

TABLE 7-1: REGISTERS ASSOCIATED WITH TIMER0

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR	Value on All Other Resets
01h	TMR0	Timer0 module register								xxxx xxxx	uuuu uuuu
0Bh/8Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
81h	OPTION	$\overline{\text{RBPU}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
85h	TRISA	—	—	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	---1 1111	---1 1111

Legend: — = Unimplemented locations, read as ‘0’, x = unknown, u = unchanged.

Note: Shaded bits are not used by TMR0 module.

8.4 Comparator Response Time

Response time is the minimum time, after selecting a new reference voltage or input source, before the comparator output has a valid level. If the internal reference is changed, the maximum delay of the internal voltage reference must be considered when using the comparator outputs, otherwise the maximum delay of the comparators should be used (Table 13-1 **).**

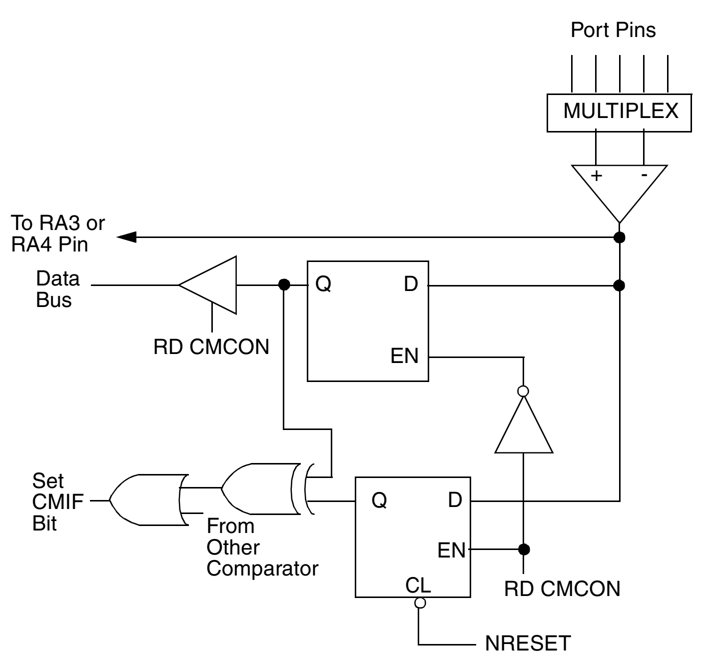
8.5 Comparator Outputs

The comparator outputs are read through the CMCON register. These bits are read only. The comparator outputs may also be directly output to the RA3 and RA4 I/O pins. When the CM<2:0> = 110, multiplexors in the output path of the RA3 and RA4 pins will switch and the output of each pin will be the unsynchronized output of the comparator. The uncertainty of each of the comparators is related to the input offset voltage and the response time given in the specifications. Figure 8-3 shows the comparator output block diagram.

The TRISA bits will still function as an output enable/disable for the RA3 and RA4 pins while in this mode.

Note 1:	When reading the PORT register, all pins configured as analog inputs will read as a '0'. Pins configured as digital inputs will convert an analog input according to the Schmitt Trigger input specification.
2:	Analog levels on any pin that is defined as a digital input may cause the input buffer to consume more current than is specified.

FIGURE 8-3: COMPARATOR OUTPUT BLOCK DIAGRAM



10.1 Configuration Bits

The configuration bits can be programmed (read as '0') or left unprogrammed (read as '1') to select various device configurations. These bits are mapped in program memory location 2007h.

The user will note that address 2007h is beyond the user program memory space. In fact, it belongs to the special test/configuration memory space (2000h – 3FFFh), which can be accessed only during programming.

REGISTER 10-1: CONFIGURATION WORD

CP1	CP0(2)	CP1	CP0(2)	CP1	CP0(2)	—	BODEN(1)	CP1	CP0(2)	$\overline{\text{PWRTE}}$(1)	WDTE	F0SC1	F0SC0
bit13													bit0

CONFIG REGISTER: Address 2007h

bit 13-8, 5-4: **CP1:CP0 Pairs:** Code protection bit pairs(2)

Code protection for 2K program memory
- `11` = Program memory code protection off
- `10` = 0400h-07FFh code protected
- `01` = 0200h-07FFh code protected
- `00` = 0000h-07FFh code protected

Code protection for 1K program memory
- `11` = Program memory code protection off
- `10` =Program memory code protection on
- `01` = 0200h-03FFh code protected
- `00` = 0000h-03FFh code protected

Code protection for 0.5K program memory
- `11` = Program memory code protection off
- `10` = Program memory code protection off
- `01` = Program memory code protection off
- `00` = 0000h-01FFh code protected

bit 7: **Unimplemented**: Read as '1'

bit 6: **BODEN**: Brown-out Reset Enable bit (1)
- `1` = BOD enabled
- `0` = BOD disabled

bit 3: **$\overline{\text{PWRTE}}$**: Power-up Timer Enable bit (1)
- `1` = PWRT disabled
- `0` = PWRT enabled

bit 2: **WDTE**: Watchdog Timer Enable bit
- `1` = WDT enabled
- `0` = WDT disabled

bit 1-0: **FOSC1:FOSC0**: Oscillator Selection bits
- `11` = RC oscillator
- `10` = HS oscillator
- `01` = XT oscillator
- `00` = LP oscillator

Note 1: Enabling Brown-out Reset automatically enables Power-up Timer (PWRT), regardless of the value of bit $\overline{\text{PWRTE}}$. Ensure the Power-up Timer is enabled anytime Brown-out Reset is enabled.

2: All of the CP<1:0> pairs have to be given the same value to enable the code protection scheme listed.

10.2 Oscillator Configurations

10.2.1 OSCILLATOR TYPES

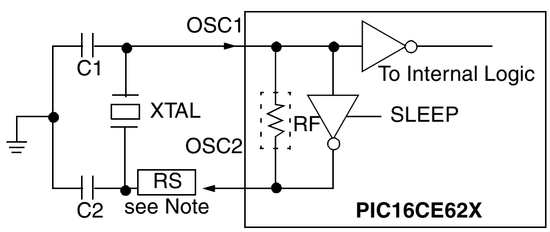
The PIC16CE62X can be operated in four different oscillator options. The user can program two configuration bits (FOSC1 and FOSC0) to select one of these four modes:

- LP Low Power Crystal
- XT Crystal/Resonator
- HS High Speed Crystal/Resonator
- RC Resistor/Capacitor

10.2.2 CRYSTAL OSCILLATOR / CERAMIC RESONATORS

In XT, LP or HS modes, a crystal or ceramic resonator is connected to the OSC1 and OSC2 pins to establish oscillation (Figure 10-1). The PIC16CE62X oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source to drive the OSC1 pin (Figure 10-2).

FIGURE 10-1: CRYSTAL OPERATION (OR CERAMIC RESONATOR) (HS, XT OR LP OSC CONFIGURATION)



See Table 10-1 and Table 10-2 for recommended values of C1 and C2.

Note: A series resistor may be required for AT strip cut crystals.

FIGURE 10-2: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)

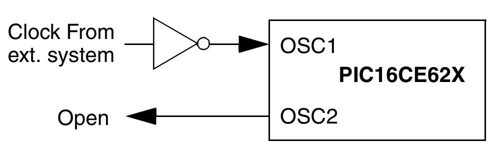


TABLE 10-1: CERAMIC RESONATORS, PIC16CE62X

Ranges Tested:			
Mode	**Freq**	**OSC1**	**OSC2**
XT	455 kHz 2.0 MHz 4.0 MHz	68 - 100 pF 15 - 68 pF 15 - 68 pF	68 - 100 pF 15 - 68 pF 15 - 68 pF
HS	8.0 MHz 16.0 MHz	10 - 68 pF 10 - 22 pF	10 - 68 pF 10 - 22 pF
These values are for design guidance only. See notes at bottom of page.			

TABLE 10-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR, PIC16CE62X

Osc Type	Crystal Freq	Cap. Range C1	Cap. Range C2
LP	32 kHz	33 pF	33 pF
	200 kHz	15 pF	15 pF
XT	200 kHz	47-68 pF	47-68 pF
	1 MHz	15 pF	15 pF
	4 MHz	15 pF	15 pF
HS	4 MHz	15 pF	15 pF
	8 MHz	15-33 pF	15-33 pF
	20 MHz	15-33 pF	15-33 pF
These values are for design guidance only. See notes at bottom of page.			

1. Recommended values of C1 and C2 are identical to the ranges tested table.
2. Higher capacitance increases the stability of oscillator, but also increases the start-up time.
3. Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.
4. Rs may be required in HS mode, as well as XT mode, to avoid overdriving crystals with low drive level specification.

10.2.3 EXTERNAL CRYSTAL OSCILLATOR CIRCUIT

Either a prepackaged oscillator can be used or a simple oscillator circuit with TTL gates can be built. Prepackaged oscillators provide a wide operating range and better stability. A well-designed crystal oscillator will provide good performance with TTL gates. Two types of crystal oscillator circuits can be used; one with series resonance or one with parallel resonance.

Figure 10-3 shows implementation of a parallel resonant oscillator circuit. The circuit is designed to use the fundamental frequency of the crystal. The 74AS04 inverter performs the 180° phase shift that a parallel oscillator requires. The 4.7 kΩ resistor provides the negative feedback for stability. The 10 kΩ potentiometers bias the 74AS04 in the linear region. This could be used for external oscillator designs.

FIGURE 10-3: EXTERNAL PARALLEL RESONANT CRYSTAL OSCILLATOR CIRCUIT

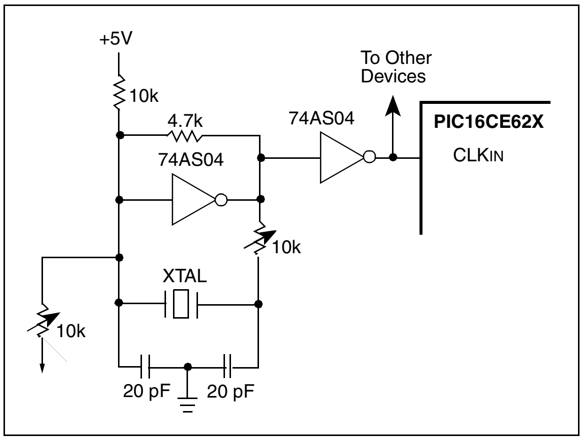
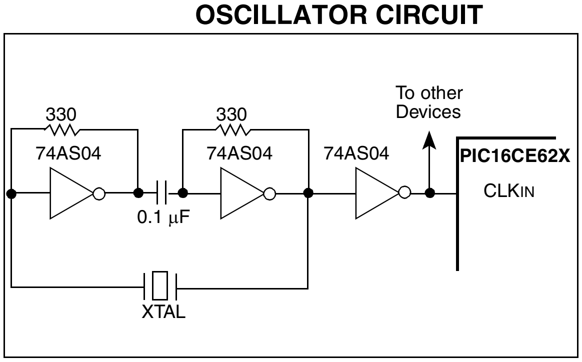


Figure 10-4 shows a series resonant oscillator circuit. This circuit is also designed to use the fundamental frequency of the crystal. The inverter performs a 180° phase shift in a series resonant oscillator circuit. The 330 kΩ resistors provide the negative feedback to bias the inverters in their linear region.

FIGURE 10-4: EXTERNAL SERIES RESONANT CRYSTAL OSCILLATOR CIRCUIT



10.2.4 RC OSCILLATOR

For timing insensitive applications the “RC” device option offers additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor (Rext) and capacitor (Cext) values, and the operating temperature. In addition to this, the oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low Cext values. The user also needs to take into account variation due to tolerance of external R and C components used. Figure 10-5 shows how the R/C combination is connected to the PIC16CE62X. For Rext values below 2.2 kΩ, the oscillator operation may become unstable, or stop completely. For very high Rext values (i.e., 1 MΩ), the oscillator becomes sensitive to noise, humidity and leakage. Thus, we recommend to keep Rext between 3 kΩ and 100 kΩ.

Although the oscillator will operate with no external capacitor (Cext = 0 pF), we recommend using values above 20 pF for noise and stability reasons. With no or small external capacitance, the oscillation frequency can vary dramatically due to changes in external capacitances, such as PCB trace capacitance or package lead frame capacitance.

See Section 14.0 for RC frequency variation from part to part due to normal process variation. The variation is larger for larger R (since leakage current variation will affect RC frequency more for large R) and for smaller C (since variation of input capacitance will affect RC frequency more).

See Section 14.0 for variation of oscillator frequency due to VDD for given Rext/Cext values, as well as frequency variation due to operating temperature for given R, C, and VDD values.

The oscillator frequency, divided by 4, is available on the OSC2/CLKOUT pin and can be used for test purposes or to synchronize other logic (Figure 3-2 for waveform).

FIGURE 10-5: RC OSCILLATOR MODE

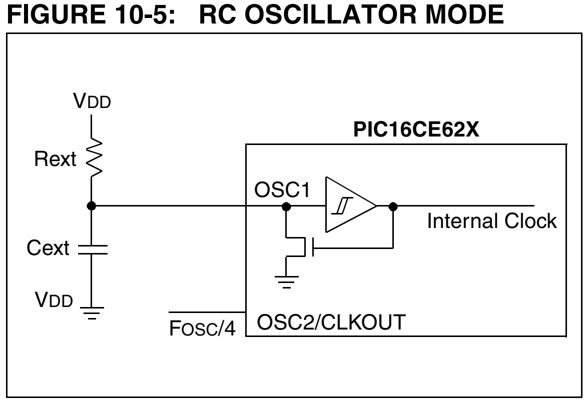


TABLE 10-5: INITIALIZATION CONDITION FOR SPECIAL REGISTERS

Condition	Program Counter	STATUS Register	PCON Register
Power-on Reset	000h	0001 1xxx	---- --0x
$\overline{MCLR}$ reset during normal operation	000h	000u uuuu	---- --uu
$\overline{MCLR}$ reset during SLEEP	000h	0001 0uuu	---- --uu
WDT reset	000h	0000 uuuu	---- --uu
WDT Wake-up	PC + 1	uuu0 0uuu	---- --uu
Brown-out Reset	000h	000x xuuu	---- --u0
Interrupt Wake-up from SLEEP	PC + 1(1)	uuu1 0uuu	---- --uu

Legend: u = unchanged, x = unknown, - = unimplemented bit, reads as ‘0’.

Note 1: When the wake-up is due to an interrupt and global enable bit, GIE is set and the PC is loaded with the interrupt vector (0004h) after execution of PC+1.

TABLE 10-6: INITIALIZATION CONDITION FOR REGISTERS

Register	Address	Power-on Reset	• $\overline{MCLR}$ Reset during normal operation • $\overline{MCLR}$ Reset during SLEEP • WDT Reset • Brown-out Reset (1)	• Wake-up from SLEEP through interrupt • Wake-up from SLEEP through WDT time-out
W	-	xxxx xxxx	uuuu uuuu	uuuu uuuu
INDF	00h	-	-	-
TMR0	01h	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCL	02h	0000 0000	0000 0000	PC + 1(3)
STATUS	03h	0001 1xxx	000q quuu(4)	uuuq quuu(4)
FSR	04h	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTA	05h	---x xxxx	---u uuuu	---u uuuu
PORTB	06h	xxxx xxxx	uuuu uuuu	uuuu uuuu
CMCON	1Fh	00-- 0000	00-- 0000	uu-- uuuu
PCLATH	0Ah	---0 0000	---0 0000	---u uuuu
INTCON	0Bh	0000 000x	0000 000u	uuuu uqqq(2)
PIR1	0Ch	-0-- ----	-0-- ----	-q-- ----(2,5)
OPTION	81h	1111 1111	1111 1111	uuuu uuuu
TRISA	85h	---1 1111	---1 1111	---u uuuu
TRISB	86h	1111 1111	1111 1111	uuuu uuuu
PIE1	8Ch	-0-- ----	-0-- ----	-u-- ----
PCON	8Eh	---- --0x	---- --uq(1,6)	---- --uu
EEINTF	90h	---- -111	---- -111	---- -111
VRCON	9Fh	000- 0000	000- 0000	uuu- uuuu

Legend: u = unchanged, x = unknown, - = unimplemented bit, reads as ‘0’,q = value depends on condition.

Note 1: If V_{DD} goes too low, Power-on Reset will be activated and registers will be affected differently.

2: One or more bits in INTCON, PIR1 and/or PIR2 will be affected (to cause wake-up).

3: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

4: See Table 10-5 for reset value for specific condition.

5: If wake-up was due to comparator input changing , then bit 6 = 1. All other interrupts generating a wake-up will cause bit 6 = u.

6: If reset was due to brown-out, then PCON bit 0 = 0. All other resets will cause bit 0 = u.

11.0 INSTRUCTION SET SUMMARY

Each PIC16CE62X instruction is a 14-bit word divided into an OPCODE which specifies the instruction type and one or more operands which further specify the operation of the instruction. The PIC16CE62X instruction set summary in Table 11-2 lists **byte-oriented**, **bit-oriented**, and **literal and control** operations. Table 11-1 shows the opcode field descriptions.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator specifies which file register is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is zero, the result is placed in the W register. If 'd' is one, the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator which selects the number of the bit affected by the operation, while 'f' represents the number of the file in which the bit is located.

For **literal and control** operations, 'k' represents an eight or eleven bit constant or literal value.

TABLE 11-1: OPCODE FIELD DESCRIPTIONS

Field	Description
`f`	Register file address (0x00 to 0x7F)
`W`	Working register (accumulator)
`b`	Bit address within an 8-bit file register
`k`	Literal field, constant data or label
`x`	Don't care location (= 0 or 1) The assembler will generate code with x = 0. It is the recommended form of use for compatibility with all Microchip software tools.
`d`	Destination select; d = 0: store result in W, d = 1: store result in file register f. Default is d = 1
`label`	Label name
`TOS`	Top of Stack
`PC`	Program Counter
`PCLATH`	Program Counter High Latch
`GIE`	Global Interrupt Enable bit
`WDT`	Watchdog Timer/Counter
$\overline{\texttt{TO}}$	Time-out bit
$\overline{\texttt{PD}}$	Power-down bit
`dest`	Destination either the W register or the specified register file location
[ ]	Options
( )	Contents
$\rightarrow$	Assigned to
< >	Register bit field
$\in$	In the set of
italics	User defined term (font is courier)

The instruction set is highly orthogonal and is grouped into three basic categories:

- **Byte-oriented** operations
- **Bit-oriented** operations
- **Literal and control** operations

All instructions are executed within one single instruction cycle, unless a conditional test is true or the program counter is changed as a result of an instruction. In this case, the execution takes two instruction cycles with the second cycle executed as a NOP. One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 4 MHz, the normal instruction execution time is 1 μs. If a conditional test is true or the program counter is changed as a result of an instruction, the instruction execution time is 2 μs.

Table 11-1 lists the instructions recognized by the MPASM assembler.

Figure 11-1 shows the three general formats that the instructions can have.

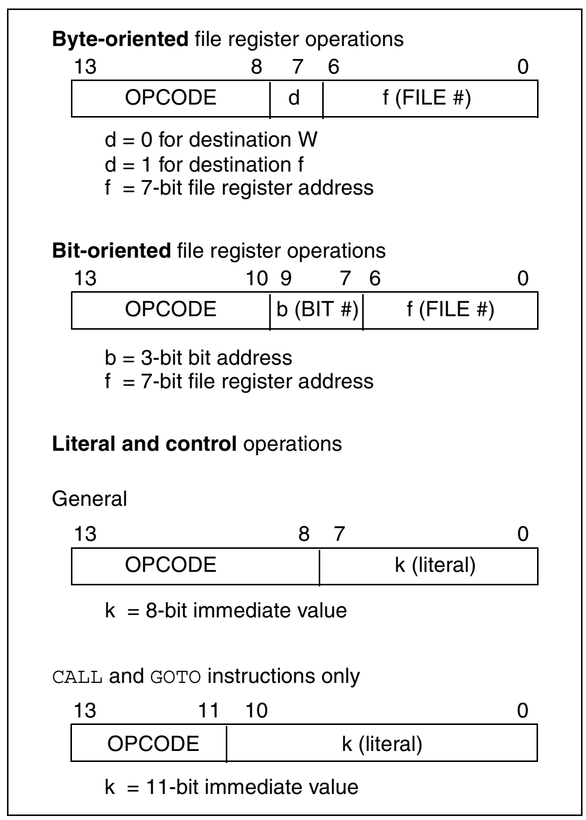
> **Note:** To maintain upward compatibility with future PIC® MCU products, do not use the `OPTION` and `TRIS` instructions.

All examples use the following format to represent a hexadecimal number:

0xhh

where h signifies a hexadecimal digit.

FIGURE 11-1: GENERAL FORMAT FOR INSTRUCTIONS



BCF — Bit Clear f

Syntax:	[*label*] BCF f,b
Operands:	$0 \le f \le 127$ $0 \le b \le 7$
Operation:	$0 \rightarrow$ (f<b>)
Status Affected:	None
Encoding:	`01` `00bb` `bfff` `ffff`
Description:	Bit 'b' in register 'f' is cleared.
Words:	1
Cycles:	1
Example	`BCF FLAG_REG, 7` Before Instruction FLAG_REG = 0xC7 After Instruction FLAG_REG = 0x47

BSF — Bit Set f

Syntax:	[*label*] BSF f,b
Operands:	$0 \le f \le 127$ $0 \le b \le 7$
Operation:	$1 \rightarrow$ (f<b>)
Status Affected:	None
Encoding:	`01` `01bb` `bfff` `ffff`
Description:	Bit 'b' in register 'f' is set.
Words:	1
Cycles:	1
Example	`BSF FLAG_REG, 7` Before Instruction FLAG_REG = 0x0A After Instruction FLAG_REG = 0x8A

BTFSC — Bit Test, Skip if Clear

Syntax:	[*label*] BTFSC f,b
Operands:	$0 \le f \le 127$ $0 \le b \le 7$
Operation:	skip if (f<b>) = 0
Status Affected:	None
Encoding:	`01` `10bb` `bfff` `ffff`
Description:	If bit 'b' in register 'f' is '0', then the next instruction is skipped. If bit 'b' is '0', then the next instruction fetched during the current instruction execution is discarded, and a `NOP` is executed instead, making this a two-cycle instruction.
Words:	1
Cycles:	1(2)
Example	see below

```
HERE    BTFSC  FLAG,1
FALSE   GOTO   PROCESS_CODE
TRUE    •
        •
        •
```

Before Instruction
PC = address `HERE`
After Instruction
if FLAG<1> = 0,
PC = address `TRUE`
if FLAG<1>=1,
PC = address `FALSE`

13.1 DC CHARACTERISTICS: PIC16CE62X-04 (Commercial, Industrial, Extended) PIC16CE62X-20 (Commercial, Industrial, Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature –40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and –40°C ≤ TA ≤ +125°C for extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	VDD	Supply Voltage	3.0	–	5.5	V	See Figure 13-1 through Figure 13-3
D002	VDR	RAM Data Retention Voltage (Note 1)	–	1.5*	–	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure Power-on Reset	–	VSS	–	V	See section on power-on reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	–	–	V/ms	See section on power-on reset for details
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D010	IDD	Supply Current (Note 2, 4)	– – – – – –	1.2 0.4 1.0 4.0 4.0 35	2.0 1.2 2.0 6.0 7.0 70	mA mA mA mA mA μA	FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT osc mode, (Note 4)* FOSC = 4 MHz, VDD = 3.0V, WDT disabled, XT osc mode, (Note 4) FOSC = 10 MHz, VDD = 3.0V, WDT disabled, HS osc mode, (Note 6) FOSC = 20 MHz, VDD = 4.5V, WDT disabled, HS osc mode FOSC = 20 MHz, VDD = 5.5V, WDT disabled*, HS osc mode FOSC = 32 kHz, VDD = 3.0V, WDT disabled, LP osc mode
D020	IPD	Power Down Current (Note 3)	– – – –	– – – –	2.2 5.0 9.0 15	μA μA μA μA	VDD = 3.0V VDD = 4.5V* VDD = 5.5V VDD = 5.5V Extended
D022 D022A D023 D023A 	ΔIWDT ΔIBOR ΔICOMP ΔIVREF ΔIEE Write ΔIEE Read ΔIEE ΔIEE	WDT Current (Note 5) Brown-out Reset Current (Note 5) Comparator Current for each Comparator (Note 5) VREF Current (Note 5) Operating Current Operating Current Standby Current Standby Current	– – – – – – – –	6.0 75 30 80	10 12 125 60 135 3 1 30 100	μA μA μA μA μA mA mA μA μA	VDD = 4.0V (125°C) $\overline{\text{BOD}}$ enabled, VDD = 5.0V VDD = 4.0V VDD = 4.0V VCC = 5.5V, SCL = 400 kHz VCC = 3.0V, EE VDD = VCC VCC = 3.0V, EE VDD = VCC
1A	FOSC	LP Oscillator Operating Frequency RC Oscillator Operating Frequency XT Oscillator Operating Frequency HS Oscillator Operating Frequency	0 0 0 0	– – – –	200 4 4 20	kHz MHz MHz MHz	All temperatures All temperatures All temperatures All temperatures

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: The power down current in SLEEP mode does not depend on the oscillator type. Power down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

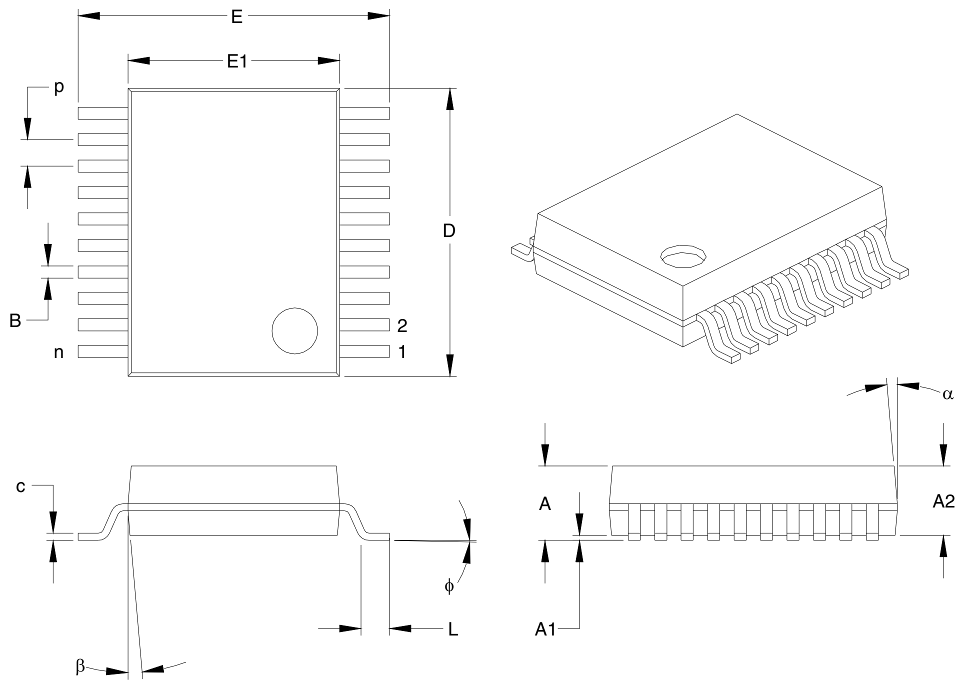
4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.

20-Lead Plastic Shrink Small Outline (SS) – 209 mil, 5.30 mm (SSOP)

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	INCHES*			MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		20			20	
Pitch	p		.026			0.66	
Overall Height	A	.068	.073	.078	1.73	1.85	1.98
Molded Package Thickness	A2	.064	.068	.072	1.63	1.73	1.83
Standoff	A1	.002	.006	.010	0.05	0.15	0.25
Overall Width	E	.299	.309	.322	7.59	7.85	8.18
Molded Package Width	E1	.201	.207	.212	5.11	5.25	5.38
Overall Length	D	.278	.284	.289	7.06	7.20	7.34
Foot Length	L	.022	.030	.037	0.56	0.75	0.94
Lead Thickness	c	.004	.007	.010	0.10	0.18	0.25
Foot Angle	φ	0	4	8	0.00	101.60	203.20
Lead Width	B	.010	.013	.015	0.25	0.32	0.38
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

*Controlling Parameter

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.

JEDEC Equivalent: MO-150

Drawing No. C04-072

NOTES:

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

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Printed on recycled paper.

ISBN: 9781620769768

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